BUK7Y13-40B



N-channel TrenchMOS standard level FET

Rev. 03 — 26 May 2008

Product data sheet

1. Product profile

1.1 General description

Standard level N-channel enhancement mode Field-Effect Transistor (FET) in a plastic package using Nexperia High-Performance Automotive (HPA) TrenchMOS technology. This product has been designed and qualified to the appropriate AEC standard for use in automotive critical applications.

1.2 Features and benefits

- 175 °C rated
- Suitable for standard level gate drive sources
- Q101 compliant
- Suitable for thermally demanding environments due to 175 °C rating

1.3 Applications

- 12 V loads
- Automotive ABS systems
- Fuel pump and injection
- Air bag
- Automotive transmission control
- Motors, lamps and solenoids

1.4 Quick reference data

Table 1. Quick reference

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V_{DS}	drain-source voltage	$T_j \ge 25~^{\circ}C;~T_j \le 175~^{\circ}C$	-	-	40	V
I _D	drain current	$V_{GS} = 10 \text{ V}; T_{mb} = 25 \text{ °C};$ see <u>Figure 1</u> and <u>4</u>	-	-	58	Α
P _{tot}	total power dissipation	T _{mb} = 25 °C; see <u>Figure 2</u>	-	-	85	W
Dynamic	characteristics					
Q_{GD}	gate-drain charge	$I_D = 10 \text{ A}; V_{DS} = 32 \text{ V};$ $V_{GS} = 10 \text{ V}; \text{ see } \frac{\text{Figure } 14}{\text{ Figure } 14}$	-	5	-	nC
Static ch	aracteristics					
R _{DSon}	drain-source on-state resistance	V_{GS} = 10 V; I_D = 25 A; T_j = 25 °C; see <u>Figure 13</u> and <u>12</u>	-	11	13	mΩ
Avalanch	e ruggedness					
E _{DS(AL)S}	non-repetitive drain-source avalanche energy	$\begin{split} I_D &= 58 \text{ A; } V_{\text{sup}} \leq 40 \text{ V;} \\ R_{\text{GS}} &= 50 \Omega; V_{\text{GS}} = 10 \text{ V;} \\ T_{j(\text{init})} &= 25 ^{\circ}\text{C; } \text{ unclamped} \end{split}$	-	-	85	mJ



2. Pinning information

Table 2. Pinning

Pin	Symbol	Description	Simplified outline	Graphic symbol
1, 2, 3	S	source	mb	D
4	G	gate		
mb	D	mounting base; connected to drain		mbb076 S
			SOT669 (LFPAK)	

3. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
BUK7Y13-40B	LFPAK	plastic single-ended surface-mounted package (LFPAK); 4 leads	SOT669

4. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DS}	drain-source voltage	$T_j \ge 25 ^{\circ}C; T_j \le 175 ^{\circ}C$	-	40	V
V_{DGR}	drain-gate voltage	$R_{GS} = 20 \text{ k}\Omega$	-	40	V
V_{GS}	gate-source voltage		20	20	V
I_D	drain current	T_{mb} = 25 °C; V_{GS} = 10 V; see <u>Figure 1</u> and <u>4</u>	-	58	Α
		T_{mb} = 175 °C; V_{GS} = 10 V; see <u>Figure 1</u>	-	41	Α
I_{DM}	peak drain current	T_{mb} = 25 °C; $t_p \le 10 \mu s$; pulsed; see Figure 4	-	234	Α
P _{tot}	total power dissipation	T _{mb} = 25 °C; see <u>Figure 2</u>	-	85	W
T _{stg}	storage temperature		-55	175	°C
Tj	junction temperature		-55	175	°C
Avalanc	he ruggedness				
E _{DS(AL)S}	non-repetitive drain-source avalanche energy	I_D = 58 A; V_{sup} ≤ 40 V; R_{GS} = 50 Ω; V_{GS} = 10 V; $T_{j(init)}$ = 25 °C; unclamped	-	85	mJ
E _{DS(AL)R}	repetitive drain-source avalanche energy	see <u>Figure 3</u>	[1][2] - [3]	-	J
Source-	drain diode				
I _S	source current	T _{mb} = 25 °C	-	58	Α
I _{SM}	peak source current	$t_p \le 10 \ \mu s$; pulsed; T_{mb} = 25 °C	-	234	Α

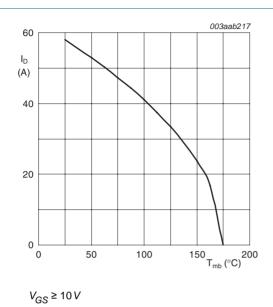
- [1] Single-pulse avalanche rating limited by maximum junction temperature of 175 °C.
- [2] Repetitive avalanche rating limited by an average junction temperature of 170 °C.
- [3] Refer to application note AN10273 for further information.

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T_{mb} (°C)

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0 50 100 150

120

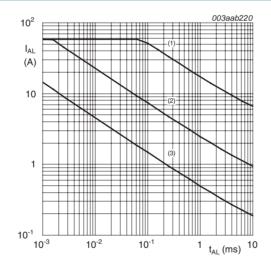
80

P_{der}

 $P_{der} = \frac{P_{tot}}{P_{tot(25^{\circ}C)}} \times 100 \%$

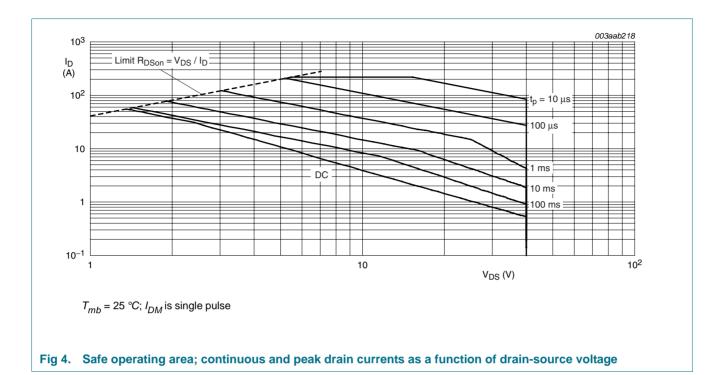
Fig 1. Continuous drain current as a function of mounting base temperature

Fig 2. Normalized total power dissipation as a function of mounting base temperature



- (1) Single-pulse; $T_i = 25 \, ^{\circ}C$.
- (2) Single-pulse; $T_i = 150 \, ^{\circ}\text{C}$.
- (3) Repetitive.

Fig 3. Single-shot and repetitive avalanche rating; avalanche current as a function of avalanche period



5. Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
R _{th(j-mb)}	thermal resistance from junction to mounting base	see <u>Figure 5</u>	-	-	1.8	K/W

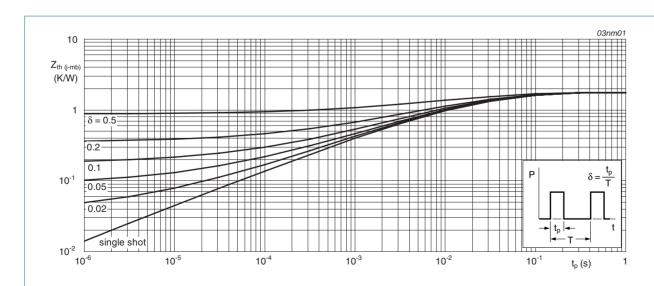


Fig 5. Transient thermal impedance from junction to mounting base as a function of pulse duration

6. Characteristics

Table 6. Characteristics

Table 6.	Characteristics					
Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Static cha	racteristics					
$V_{(BR)DSS}$	drain-source breakdown voltage	$I_D = 250 \mu A; V_{GS} = 0 V;$ $T_j = 25 ^{\circ}C$	40	-	-	V
		$I_D = 250 \mu A; V_{GS} = 0 V;$ $T_j = -55 °C$	36	-	-	V
$V_{GS(th)}$	gate-source threshold voltage	I_D = 1 mA; V_{DS} = V_{GS} ; T_j = 25 °C; see <u>Figure 10</u> and <u>11</u>	2	3	4	V
		$I_D = 1$ mA; $V_{DS} = V_{GS}$; $T_j = -55$ °C; see <u>Figure 10</u>	-	-	4.4	V
		$I_D = 1$ mA; $V_{DS} = V_{GS}$; $T_j = 175$ °C; see <u>Figure 10</u>	1	-	-	V
I _{DSS}	drain leakage current	$V_{DS} = 40 \text{ V}; V_{GS} = 0 \text{ V};$ $T_j = 175 ^{\circ}\text{C}$	-	-	500	μΑ
		V_{DS} = 40 V; V_{GS} = 0 V; T_j = 25 °C	-	0.02	1	μΑ
I _{GSS}	gate leakage current	$V_{DS} = 0 \text{ V}; V_{GS} = 20 \text{ V}; T_j = 25 ^{\circ}\text{C}$	-	2	100	nA
		$V_{DS} = 0 \text{ V}; V_{GS} = -20 \text{ V};$ $T_j = 25 \text{ °C}$	-	2	100	nA
R _{DSon}	drain-source on-state resistance	$V_{GS} = 10 \text{ V; } I_D = 25 \text{ A;}$ $T_j = 175 \text{ °C; see } \frac{\text{Figure 12}}{\text{Figure 12}}$	-	-	25	mΩ
		$V_{GS} = 10 \text{ V; } I_D = 25 \text{ A; } T_j = 25 \text{ °C;}$ see Figure 13 and 12	-	11	13	mΩ
Source-dr	ain diode					
V_{SD}	source-drain voltage	$I_S = 25 \text{ A}; V_{GS} = 25 \text{ V}; T_j = 25 \text{ °C};$ see <u>Figure 16</u>	-	0.85	1.2	V
t _{rr}	reverse recovery time	$I_S = 20 \text{ A}; dI_S/dt = 100 \text{ A/}\mu\text{s};$	-	41	-	ns
Q _r	recovered charge	$V_{GS} = 0 \text{ V}; V_{DS} = 30 \text{ V}$	-	22	-	nC
Dynamic o	characteristics					
Q _{G(tot)}	total gate charge	$I_D = 10 \text{ A}; V_{DS} = 32 \text{ V};$	-	19	-	nC
Q _{GS}	gate-source charge	V _{GS} = 10 V; see <u>Figure 14</u>	-	6	-	nC
Q _{GD}	gate-drain charge		-	5	-	nC
C _{iss}	input capacitance	V _{GS} = 0 V; V _{DS} = 25 V;	-	983	1311	pF
C _{oss}	output capacitance	$f = 1 \text{ MHz}; T_j = 25 \text{ °C};$	-	280	336	pF
C _{rss}	reverse transfer capacitance	- see <u>Figure 15</u>	-	138	189	pF
t _{d(on)}	turn-on delay time	$V_{DS} = 30 \text{ V}; R_L = 2.5 \Omega;$	-	9	-	ns
t _r	rise time	$V_{GS} = 10 \text{ V}; R_{G(ext)} = 10 \Omega$	-	25	-	ns
t _{d(off)}	turn-off delay time		-	35	-	ns
t _f	fall time		_	27	_	ns

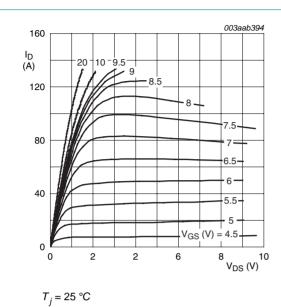


Fig 6. Output characteristics: drain current as a function of drain-source voltage; typical values

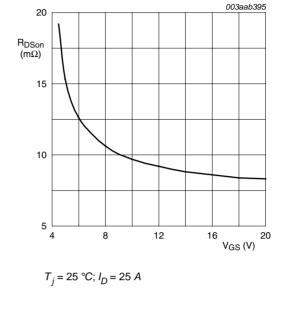


Fig 7. Drain-source on-state resistance as a function of gate-source voltage; typical values

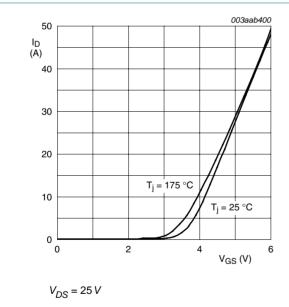
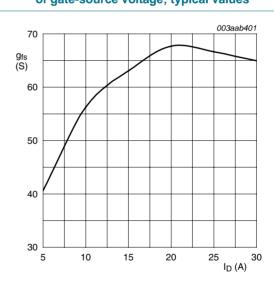


Fig 8. Transfer characteristics: drain current as a function of gate-source voltage; typical values



 $T_i = 25 \, ^{\circ}C; V_{DS} = 25 \, V$

Fig 9. Forward transconductance as a function of drain current; typical values

6 of 12

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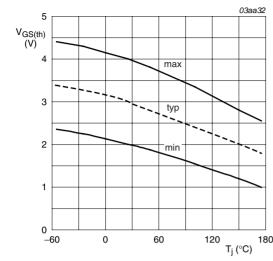
6

V_{GS} (V)

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typ

max



$$I_D = 1 mA; V_{DS} = V_{GS}$$



 10^{-1}

10-2

10-3

 10^{-4}

10⁻⁵

I_D (A)

Fig 10. Gate-source threshold voltage as a function of junction temperature

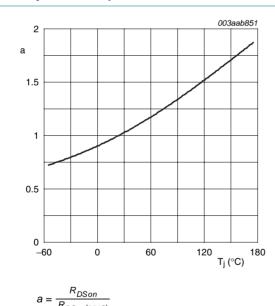


Fig 12. Normalized drain-source on-state resistance factor as a function of junction temperature



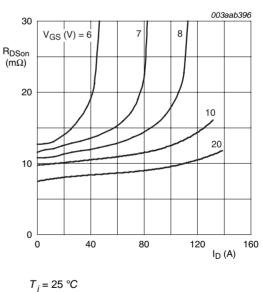
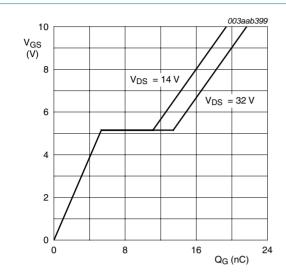
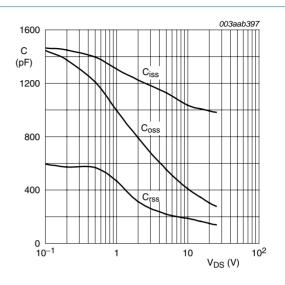


Fig 13. Drain-source on-state resistance as a function of drain current; typical values



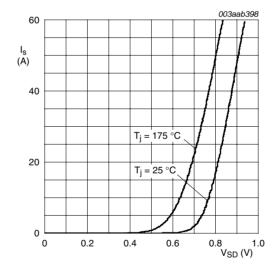
$$T_i = 25 \, ^{\circ}C; I_D = 10 \, A$$

Fig 14. Gate-source voltage as a function of gate charge; typical values



$$V_{GS} = 0 V$$
; $f = 1 MHz$

Fig 15. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values



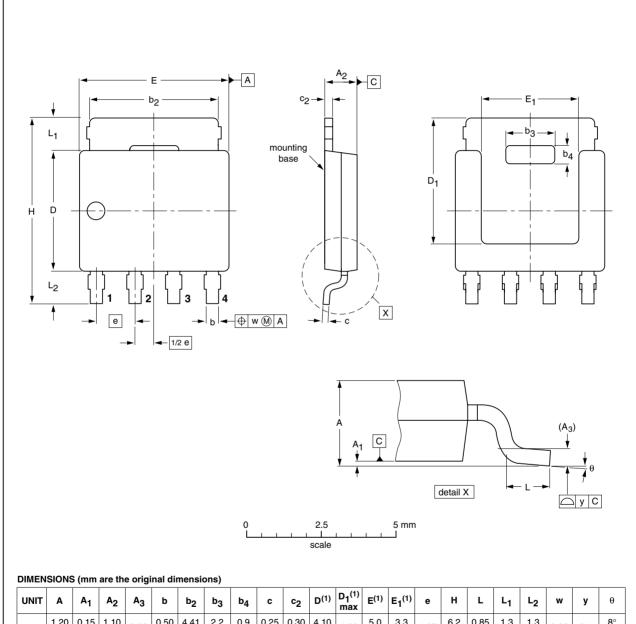
 $V_{GS} = 0 V$

Fig 16. Source current as a function of source-drain voltage; typical values

Package outline

Plastic single-ended surface-mounted package (LFPAK); 4 leads

SOT669



UNIT	A	A ₁	A ₂	A ₃	b	b ₂	b ₃	b ₄	С	c ₂	D ⁽¹⁾	D ₁ ⁽¹⁾ max	E ⁽¹⁾	E ₁ ⁽¹⁾	е	Н	L	L ₁	L ₂	w	у	θ
mm	1.20 1.01	0.15 0.00	1.10 0.95	0.25	0.50 0.35	4.41 3.62	2.2 2.0	0.9 0.7	0.25 0.19	0.30 0.24		4.20	5.0 4.8	3.3 3.1	1.27	6.2 5.8	0.85 0.40	1.3 0.8	1.3 0.8	0.25	0.1	8° 0°

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE		REFER	ENCES	EUROPEAN	ISSUE DATE	
VERSION	IEC	JEDEC	JEITA	PROJECTION	ISSUE DATE	
SOT669		MO-235			04-10-13 06-03-16	

Fig 17. Package outline SOT669 (LFPAK)

8. Revision history

Table 7. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BUK7Y13-40B_3	20080526	Product data sheet	-	BUK7Y13-40B_2
Modifications:	• <u>Table 5</u> , ma	ximum thermal resistance value	ue updated	
BUK7Y13-40B_2	20071002	Product data sheet	-	BUK7Y13-40B_1
BUK7Y13-40B_1	20070924	Product data sheet	-	-

9. Legal information

9.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions"
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